

In the Claims:

1. (Currently Amended) A semiconductor device testing socket or adapter device adapted for carrying a semiconductor device to be tested, the semiconductor device testing socket or adapter device comprising a plurality of connection pins, wherein the connection pins extend from a lower surface of a housing of the socket or adapter device in a downward direction, the connection pins being configured to be connected to a corresponding contact device by solderless surface mounting, and [[the]] end sections of the connection pins [[have]] having a shape bent back in an upward direction with respective tips of the end sections being arranged outside the housing, the bent back end sections of the connection pins viewed from [[the]] a bottom of the socket or adapter device being arranged obliquely with an angle between 30° and 60° with respect to a longitudinal axis of the socket or adapter device so as to avoid contact between a bent back end section of a first connection pin and a bent back end section of an adjacent second connection pin when the semiconductor device testing socket or adapter device is mounted to the contact device, wherein each connection pin comprises a maximum extension length of between about 0.1mm and about 1.5mm.

2. (Currently Amended) The socket or adapter device according to claim 1, wherein the socket or adapter device is a semiconductor device testing socket or a semiconductor device testing adapter, respectively, which is configured for testing a semiconductor device such that [[it]] the socket or adapter device can be loaded with a corresponding semiconductor device.

3. (Original) The socket or adapter device according to claim 2, wherein the socket or adapter device is a burn-in testing socket or a burn-in testing adapter, respectively, which is configured for performing a burn-in test and can be loaded with a corresponding semiconductor device.

4. (Previously Presented) The socket or adapter device according to claim 1, wherein the connection pins are made of a flexible or resilient material.

5. (Currently Amended) The socket or adapter device according to claim 4, wherein the ~~metal alloy~~ material includes copper and/or beryllium.

6. (Canceled)

7. (Currently Amended) The socket or adapter device according to claim 1, wherein [[the]] a device comprising the contact device is a circuit board configured to be connected to a testing apparatus.

8. (Currently Amended) The socket or adapter device according to claim 1, wherein [[the]] a device comprising the contact device is a testing apparatus.

9. (Currently Amended) A system, comprising:
at least one socket or adapter device; and

at least one semiconductor device testing apparatus, wherein the socket or adapter device comprises a plurality of connection pins which are configured to be connected to a corresponding contact device for connection to the testing apparatus, and

wherein the connection pins extend from a lower surface of a housing of the socket or adapter device in a downward direction, [[the]] end sections of the connection pins [[have]] having a shape bent back in an upward direction with respective tips of the end sections being arranged outside the housing, the bent back end sections of the connection pins viewed from [[the]] a bottom of the socket or adapter device being arranged obliquely with an angle between 30° and 60° with respect to a longitudinal axis of the socket or adapter device so as to avoid contact between a bent back end section of a first connection pin and a bent back end section of an adjacent second connection pin when the socket or adapter device is mounted to the contact device, and the connection pins are connected to the contact device by surface mounting, wherein each connection pin comprises a maximum extension length of between about 0.1mm and about 1.5mm.

10. (Previously Presented) The system according to claim 9, wherein the connection pins are connected to the contact device without soldering.
11. (Previously Presented) The system according to claim 9, wherein a device is provided such that the connection pins are pressed against the contact device.
12. (Original) The system according to claim 11, wherein the device is an appropriate screw connection.

13. (Original) The system according to claim 11, wherein the device is an appropriate clamping connection.

14. (Currently Amended) The system according to claim 10, wherein the socket or adapter device comprises a plurality of connection pins, each being connected to corresponding contact devices, and wherein the ~~connection~~ connection pins each are connected to the respectively corresponding contact devices without soldering.

15. (Currently Amended) A method for testing semiconductor devices, the method comprising:

connecting a socket or adapter device to a testing system, wherein a plurality of connection pins are connected to a corresponding contact device;

loading the socket or adapter device with a semiconductor device to be tested, wherein

the connection pins extend from a lower surface of a housing of the socket or adapter device in a downward direction, ~~the bent-back~~ end sections of the connection pins ~~[[have]]~~ having a shape bent back in an upward direction with respective tips of the end ~~section~~ sections being arranged outside the housing, the end sections of the connection pins viewed from ~~[[the]]~~ a bottom of the socket or adapter ~~device~~ being arranged obliquely with an angle between 30° and 60° with respect to a longitudinal axis of the socket or adapter device so as to avoid contact between a bent back end section of a first connection pin and a bent back end section of an adjacent second connection pin when the socket or adapter device is mounted to the contact device, and the connection of the

connection pins ~~[[too]]~~ to the contact device ~~[[are]]~~ is by solderless surface mounting,
wherein each connection pin comprises a maximum extension length of between about
0.1mm and about 1.5mm.